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PATENT NUMBER and
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U.S. UTILITY Patent Application

APPL NUM 10019299	FILING DATE 03/11/2002	CLASS 174	SUBCLASS 260	GAU 2841	EXAMINER A1-A1A
**APPLICANTS: Gotoh Johshi; Okuno Tatsuya; 252					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/JP00/04490 07/06/2000 (Gotoh Johshi)					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 194501/1999 07/08/1999					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO P67440US0	
TITLE : Underfilling material for semiconductor package					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	
		Print Claim for O.G.	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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